

ABSTRACT

POLYIMIDE RESIN, RESIN COMPOSITION USING SAME, AND
LAMINATED FILM

5 Provided are: a polyimide resin which has high heat resistance and is capable
of uniformly performing temporary adhesion over a large area with no void or the
like; a resin composition using the same; and a laminated film. The polyimide resin
of the present invention has at least an acid anhydride residue and a diamine residue
and contains a residue of a polysiloxane diamine in an amount of not less than 60%
by mole in the total amount of the diamine residue.

10 [No Suitable Figure]